

Innovating Energy Technology

http://www.fujielectric.com/products/semiconductor/ **FUJI POWER MOSFET**

Super J MOS[®] S1 series

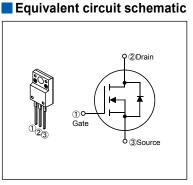
N-Channel enhancement mode power MOSFET

Features

Pb-free lead terminal **RoHS** compliant

Applications For switching

Outline Drawings [mm] TO-220F (SLS) 2.7±0.2 5.9 Ð Le las Pre-Solder 0.5 18.3 2.7 10.2 2.54 ±1 2.54 10.2 Gate
 Drain
 S~~



Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

Description	Symbol	Characteristics	Unit	Remarks
Drain Source Veltere	VDS	600	V	
Drain-Source Voltage	VDSX	600 🔿	V	V _{GS} =-30V
Continuous Drain Current	lo Rat	10.5 ±6.5	A	Tc=25°C Note*1
Continuous Drain Current		172-46月1日	A	Tc=100°C Note*1
Pulsed Drain Current	log T	19.54 P	A	
Gate-Source Voltage	VGS	5 × ±30	V	
Repetitive and Non-Repetitive Maximum Avalanche Current	TAR 2	diziet	А	Note *2
Non-Repetitive Maximum Avalanche Energy	Face PI	203.4 1	す∘ mJ	Note *3
Maximum Drain-Source dV/dt	dVos/dt	50、50	κV/μs	V _{DS} ≤ 600V
Peak Diode Recovery dV/dt	dviat Jal 200	igning15	kV/μs	Note *4
Peak Diode Recovery - di/dt	-di/dt new de	100	A/µs	Note *5
Maximum Bower Dissination tに相設計してない	m ^{tor} .	2.16	W	T _a =25°C
Maximum Power Dissipation Operating and Storage Temperature range Isolation Voltage	FD	21	vv	Tc=25°C
Operating and Storage Temperature Operation	Tch	150	°C	
Operating and Storage reinperature range	T _{stg}	-55 to +150	°C	
Isolation Voltage	Viso	2	kVrms	t=60sec, f=60Hz

Note *1 : Limited by maximum channel temperature.

Note *1 : Limited by maximum channel temperature. Note *2 : T_{ch}≤150°C, See Fig.1 and Fig.2 Note *3 : Starting T_{ch}=25°C, I_{AS}=1.4A, L=190mH, V_{DD}=60V, R_G=50Ω, See Fig.1 and Fig.2 EAS limited by maximum channel temperature and avalanche current. Note *4 : I_F≤-I_D, -di/dt=100A/µs, V_{DD}≤400V, V_{peak}≤BV_{DSS}, T_{ch}≤150°C. Note *5 : I_F≤-I_D, dV/dt=15kV/µs, V_{DD}≤400V, V_{peak}≤BV_{DSS}, T_{ch}≤150°C.

Electrical Characteristics at T_c=25°C (unless otherwise specified) Static Ratings

Description	Symbol	Conditions		min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	I _D =250μA V _{GS} =0V		600	-	-	V
Gate Threshold Voltage	V _{GS(th)}	I₀=250µA V₀s=V₀s		2.5	3.0	3.5	V
Zero Gate Voltage Drain Current	IDSS	V _{DS} =600V V _{GS} =0V	T _{ch} =25°C	-	-	25	-μA
		V _{DS} =480V V _{GS} =0V	T _{ch} =125°C	-	-	250	
Gate-Source Leakage Current	IGSS	V _{GS} = ± 30V V _{DS} =0V		-	10	100	nA
Drain-Source On-State Resistance	R _{DS(on)}	ID=3.25A VGS=10V		-	0.49	0.58	Ω
Gate resistance	Ro	f=1MHz, open drain		-	3.4	-	Ω

Dynamic Ratings

Description	Symbol	Conditions	min.	typ.	max.	Unit
Forward Transconductance	g _{fs}	I _D =3.25A V _{DS} =25V	3	6	-	S
Input Capacitance	Ciss	V _{DS} =10V V _{GS} =0V	-	510	-	
Output Capacitance	Coss		-	1130	-	
Reverse Transfer Capacitance	Crss	f=1MHz	-	100	-	
Effective output capacitance, energy related (Note *6)	C _{o(er)}	V _{GS} =0V V _{DS} =0480V	-	43	-	pF
Effective output capacitance, time related (Note *7)	C _{o(tr)}	V _{GS} =0V V _{DS} =0480V ID=constant	-	120	-	
	t _{d(on)}		-	9.5	-	
Turn-On Time	tr	V _{DD} =400V, V _{GS} =10V/0V	-	28	-	1
	td(off)	_ Ι₀=3.25A, R₀=36Ω _ See Fig.3 and Fig.4	-	73	-	ns
Turn-Off Time	tr		-	17.5	-	
Total Gate Charge	Q _G		-	21	-	
Gate-Source Charge	Q _{GS}	V _{DD} =480V, I _D =6.5A	-	7	-	nC
Gate-Drain Charge	QGD	│ V₀₅=10V │ See Fig.5	-	4.5	-	
Drain-Source crossover Charge	Qsw		-	4.5	-	

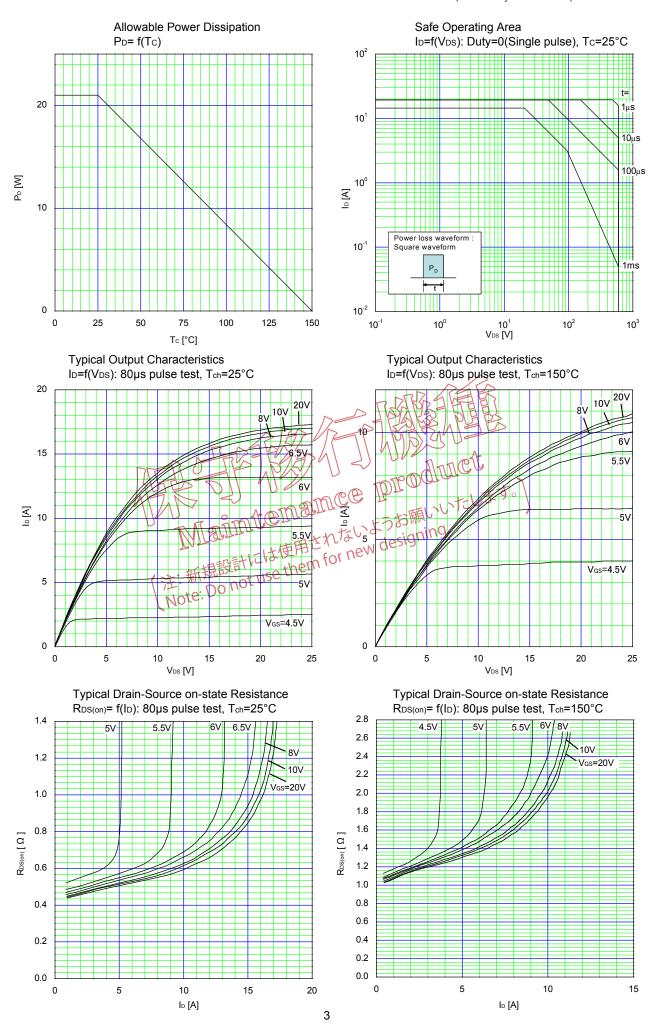
Note *6 : $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{Ds} is rising from 0 to 80% BV_{Dss}. Note *7 : $C_{o(tr)}$ is a fixed capacitance that gives the same charging times as C_{oss} while V_{Ds} is rising from 0 to 80% BV_{Dss}.

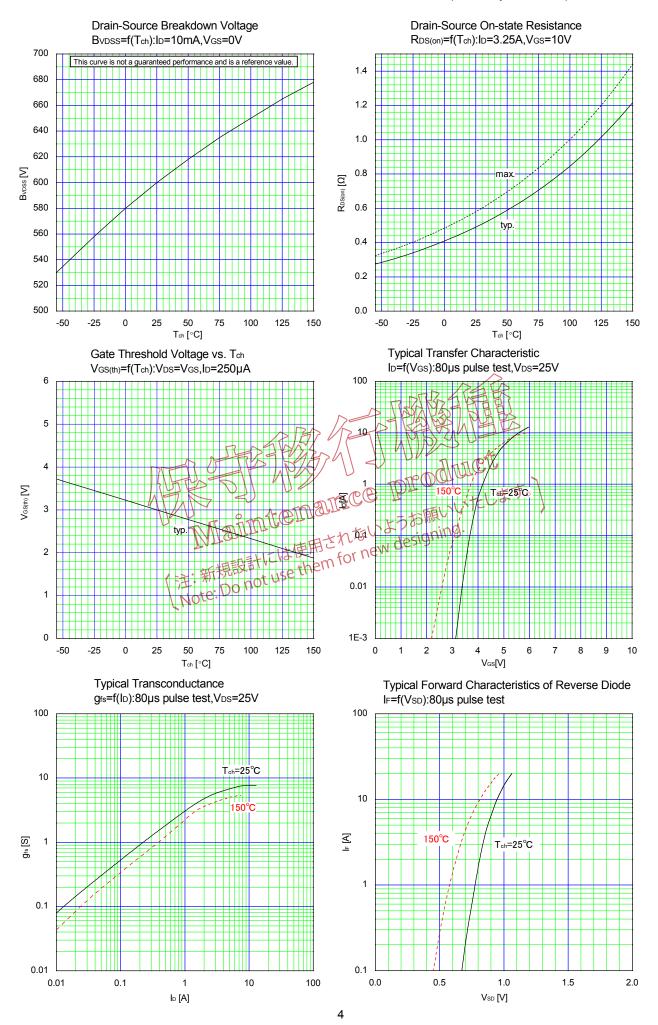
Reverse Diode

Description	Symbol	Conditions	an min.	typ.	max.	Unit
Avalanche Capability	IAV R	L=42.9mH, To=25°C See Fig. 1 and Fig.2	2.3 1.001	-	-	А
Diode Forward On-Voltage	TRO D	Ten=25°C	dituice	0.9	1.35	V
Reverse Recovery Time	t	III 20 C PL III 20 C PL IIII 20 C PL III 20 C PL IIII	in tet	275	-	ns
Reverse Recovery Charge	o MIai	Vesicitieshort, Vesicitieshov design Re=300象使用。for new design	- - -	2.7	-	μC
Peak Reverse Recovery Current	泄 新規語	See Fig.6 and Fig.7	-	18	-	А

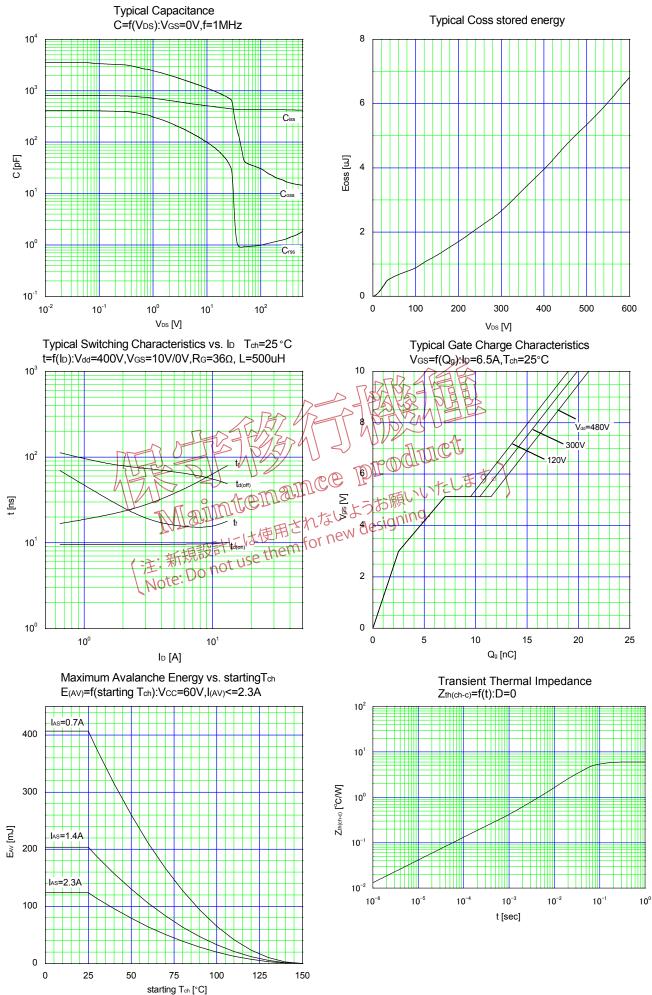
Thermal Resistance

Parameter	Symbol	min.	typ.	max.	Unit
Channel to Case	R _{th(ch-c)}	-	-	5.95	°C/W
Channel to Ambient	R _{th(ch-a)}	-	-	58	°C/W









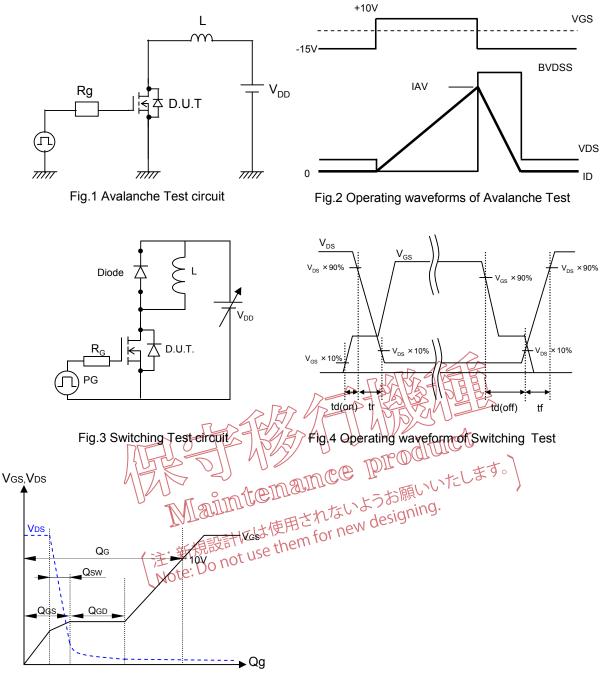


Fig.5 Operating waveform of Gate charge Test

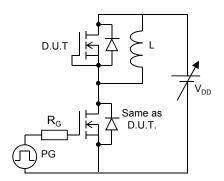


Fig.6 Reverse recovery Test circuit

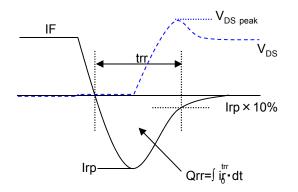
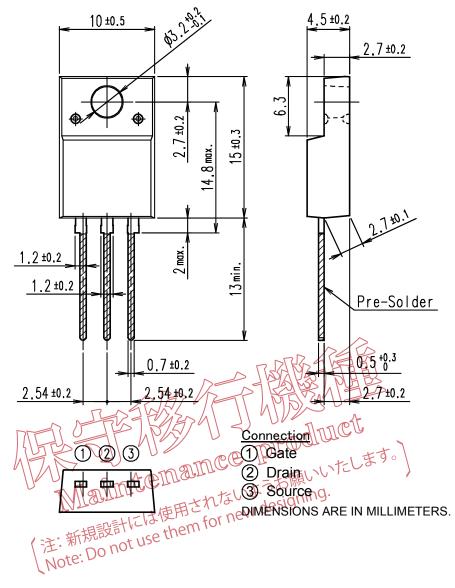
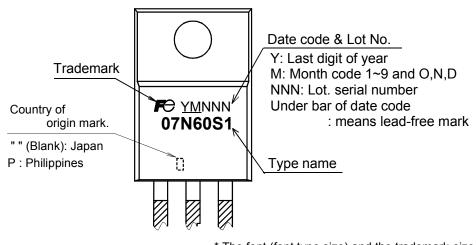


Fig.7 Operating waveform of Reverse recovery Test

Outview: TO-220F (SLS) Package







* The font (font type,size) and the trademark-size might be actually different.

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